2SK1103

Silicon N-channel junction FET

For switching circuits
Complementary to 2SJ0163

■ Features

- Low ON resistance
- Low-noise characteristics

■ Absolute Maximum Ratings $T_a = 25$ °C

Parameter	Symbol	Rating	Unit	
Gate-drain surrender voltage	V _{GDS}	-65	V	
Drain current	I_D	20	mA	
Gate current	I_G	10	mA	
Power dissipation	P_{D}	150	mW	
Channel temperature	T _{ch}	150	°C	
Storage temperature	T _{stg}	-55 to +150	°C	

■ Package

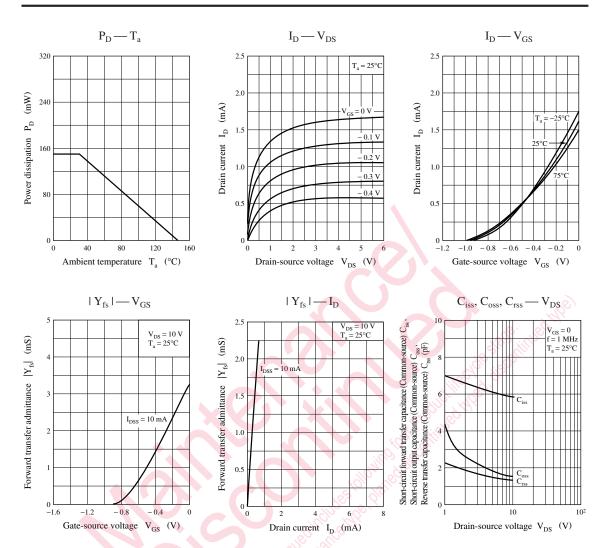
- Code
- Mini3-G1
 Pin Name
- 1: Source
- 2: Drain
- 3: Gate
- Marking Symbol: 4L

■ Electrical Characteristics $T_a = 25$ °C ± 3 °C

Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Gate-drain surrender voltage	V _{GDS}	$I_G = -10 \mu\text{A}, V_{DS} = 0$	-65			V
Drain-source current *	I _{DSS}	$V_{DS} = 10 \text{ V}, V_{GS} = 0$	0.6		6.0	mA
Gate-source cutoff current	I_{GSS}	$V_{GS} = -30 \text{ V}, V_{DS} = 0$			-10	nA
Gate-source cutoff voltage	V _{GSC}	$V_{DS} = 10 \text{ V}, I_{D} = 10 \mu\text{A}$		-1.5	-3.5	V
Forward transfer admittance	Y _{fs}	$V_{DS} = 10 \text{ V}, I_D = 1 \text{ mA}, f = 1 \text{ kHz}$	1.8	2.5		mS
Drain-source ON resistance	R _{DS(on)}	$V_{DS} = 10 \text{ mV}, V_{GS} = 0$		300		Ω
Short-circuit forward transfer capacitance	C _{iss}	$V_{DS} = 10 \text{ V}, V_{GS} = 0, f = 1 \text{ MHz}$		7		pF
(Common source)	inte					
Reverse transfer capacitance	C_{rss}			1.5		pF
(Common source)						

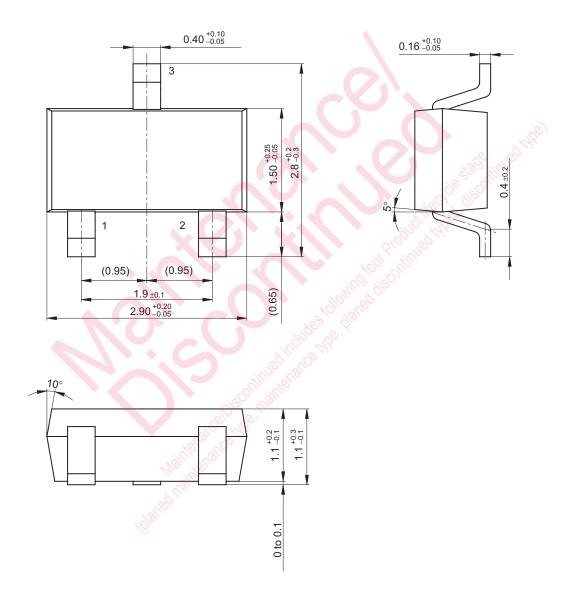
- Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7030 measuring methods for transistors.
 - 2. Observe precautions for handling. Electrostatic sensitive devices.
 - 3. *: Rank classification

Rank	Р	Q	R
I _{DSS} (mA)	0.6 to 1.5	1.0 to 3.0	2.5 to 6.0



2 SJF00011DED

Mini3-G1 Unit: mm



SJF00011DED 3

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